- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

These J-K flip-flops are based on the master-slave principle and each has AND gate inputs for entry into the master section which are controlled by the clock pulse. The clock pulse also regulates the state of the coupling transistors which connect the master and slave sections. The sequence of operation is as follows:

- 1. Isolate slave from master
- 2. Enter information from AND gate inputs to master
- 3. Disable AND gate inputs
- 4. Transfer information from master to slave

The logical states of the J and K inputs must not be allowed to change when the clock pulse is in a high state.

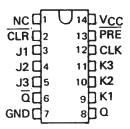
The SN5472, and the SN54H72 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 °C. The SN7472 is characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE

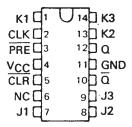
L		INP	OUTF	PUTS			
L	PRE	CLR	CLK	J	K	Q	ā
	L	Н	X	X	X	н	L
	Н	L	X	X	Х	L	н
1	L	L	X	Х	Х	H [†]	H [†]
	Н	н	T	L	L	α ₀	\overline{a}_0
	Н	Н	Л	Н	L	Н	L
	Н	Н	\mathbf{U}	L	н	L	н
L	Н	Н	л.	Н	Н	TOG	GLE

[†] This configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

SN5472 . . . J PACKAGE SN7472 . . . N PACKAGE (TOP VIEW)

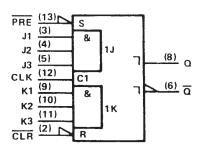


SN5472 . . . W PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol‡



[‡]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

positive logic

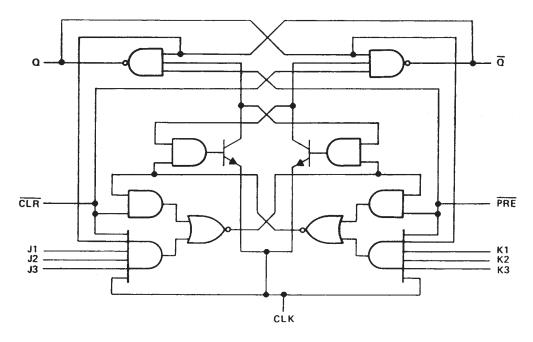
$$J = J1 \cdot J2 \cdot J3$$

 $K = K1 \cdot K2 \cdot K3$

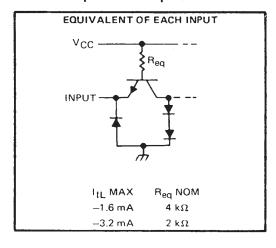


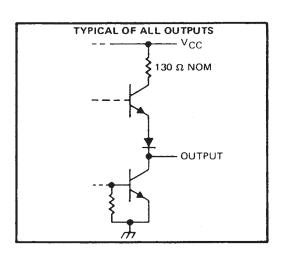
Pin numbers shown are for J and N packages.

logic diagram (positive logic)



schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	Supply voltage, VCC (see Note 1)						
	• • • • • • • • • • • • • • • • • • • •						
Operating free-air temperature:	SN54'	- 55°C to 125°C					
	SN74'						
Storage temperature range	• • • • • • • • • • • • • • • • • • • •	- 65°C to 150°C					
NOTE 1: Voltage values are with respect to							



recommended operating conditions

				SN547	2	SN7472			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5,5	4.75	5	5,25	V
VIH	High-level input voltage		2			2			٧
VIL	Low-level input voltage			8.0			8.0	٧	
ЮН	High-level output current				- 0.4			- 0.4	mA
loL	Low-level output current				16			16	mA
		CLK high	20			20			
t _w	Pulse duration	CLK low	47			47		<u> </u>	ns
		PRE or CLR	25			25			
t _{su}	Input setup time before CLK†		0			0			ns
th	Input hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS T		SN5472	2				
		TEST CONDITIONS †	MIN	TYP‡	MAX	MIN	TYP#	MAX	UNIT
VIK		V _{CC} = MIN, I ₁ = - 12 mA			- 1.5			- 1.5	٧
VOH		$V_{CC} = MIN$, $V_{1H} = 2 V$, $V_{1L} = 0.8 V$, $I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		v
VOL		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
4		V _{CC} = MAX, V ₁ = 5.5 V			1			1	mA
,	Jor K	V - MAY V - 2.4 V			40			40	μА
ΊΗ	All other	$V_{CC} = MAX$, $V_I = 2.4 V$	ſ		80			80	"^
,	Jor K	V MAY - V - 0.4 V			- 1.6			- 1.6	^
ΊL	All other	$V_{CC} = MAX$, $V_1 = 0.4 V$			- 3.2			- 3.2	mA
Ioss		V _{CC} = MAX	- 20		57	- 18		57	mΑ
lcc		V _{CC} = MAX, See Note 2		10	20		10	20	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TỌ (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax				15	20		MHz
^t PLH	PRE or CLR	Q or Q			16	25	ns
^t PHL	FRE OF CER	QUIQ	$R_L = 400 \Omega$, $C_L = 15 pF$		25	40	ns
^t PLH	CLK	Q or $\overline{\mathbf{Q}}$			16	25	ns
^t PHL	CLK	Q O Q			25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN5472J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5472J
SN5472J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN5472J
SNJ5472J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5472J
SNJ5472J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5472J
SNJ5472W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5472W
SNJ5472W.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ5472W

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SNJ5472W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ5472W.A	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025